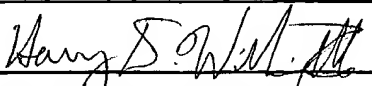


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		APPLICANT Vladimir Segal et al.						
		FILING DATE December 16, 1999		GROUP 1742				
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<small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>								

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Henry S. W. Little

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							Yes	No
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	AP							
	AQ							

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